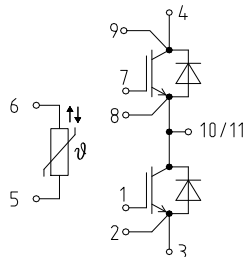
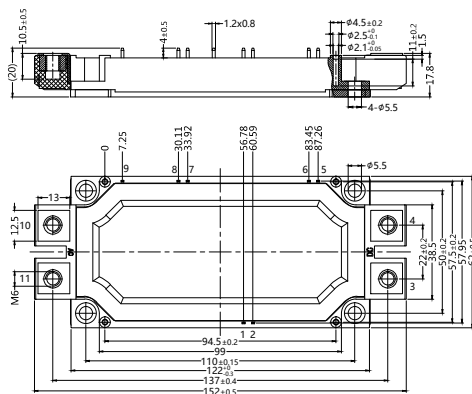


SGG300T170UC5

IGBT Modules



Dimensions in mm (1mm = 0.0394")



Symbol	Conditions	Values	Units
IGBT			
V_{CES}		1700	V
$I_{Cnom}(I_C)$	$T_C = 25(100)^{\circ}C$	375(300)	A
I_{CRM}	$T_C = 25^{\circ}C, t_P = 1ms$	600	A
V_{GES}		± 20	V
T_{Vj}		$-40 \dots +175$	$^{\circ}C$
Inverse Diode			
I_F	$T_C = 25(100)^{\circ}C$	350(300)	A
I_{FRM}	$T_C = 25^{\circ}C, t_P = 1ms$	600	A
I_{FSM}	$t_P = 10ms; sin.; T_J = 150^{\circ}C$	600	A
Module			
$I_t(RMS)$	$T_{terminal} = 80^{\circ}C$	300	A
T_{stg}		$-40 \sim 125$	$^{\circ}C$
V_{isol}	AC, 1min	4000	V

Features

- Trench FS technology
- Low switching losses
- Switching frequency upto 20kHz
- Square RBSOA, no latch up
- High short circuit capability
- Positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- Soft switching FRD diode Technology
- Package with copper base plate
- Isolation voltage 4000V

Application

- AC and DC motor control
- AC servo and robot drives
- power supplies
- welding inverters

Advantages

- space and weight savings
- reduced protection circuits

SGG300T170UC5

IGBT Modules

Characteristics

$T_C = 25^{\circ}\text{C}$, unless otherwise specified

Symbol	Conditions	min.	typ.	max.	Units
IGBT					
$V_{GE(th)}$	$V_{GE}=V_{CE}, I_C=12\text{mA}$	5.0	5.85	6.2	V
I_{CES}	$V_{GE}=0; V_{CE}=V_{CES}; T_J=25^{\circ}\text{C}$			2.0	mA
$V_{CE(TO)}$	$T_J=25^{\circ}\text{C}$		0.86	0.96	V
r_{CE}	$V_{GE}=15\text{V}, T_J=25(150)^{\circ}\text{C}$		7.00(10.1)	7.90(10.7)	m Ω
$V_{CE(sat)}$	$I_C=300\text{A}; V_{GE}=15\text{V}; \text{chip level}$		2.05	2.50	V
C_{ies}	under following conditions $V_{GE}=0, V_{CE}=25\text{V}, f=1\text{MHz}$		21.0		nF
C_{oes}			1.19		
C_{res}			0.86		
L_{CE}				20	nH
$R_{CC'+EE'}$	res., terminal-chip $T_C=25(125)^{\circ}\text{C}$		0.26(0.60)		m Ω
$t_{d(on)}$	under following conditions: $V_{CC}=900\text{V}, I_C=300\text{A}$ $R_{Gon}=R_{Goff}=1\Omega, T_J=150^{\circ}\text{C}$ $V_{GE}=\pm 15\text{V}$		295		ns
t_r			72		ns
$t_{d(off)}$			500		ns
t_f			380		ns
$E_{on}(E_{off})$			54.7(58.1)		mJ
Inverse Diode under following conditions:		1700			V
V_{RRM} $V_F = V_{EC}$	$I_F=300\text{A}; V_{GE}=0\text{V}; T_J=25^{\circ}\text{C}$		2.98	3.50	
$V_{(FO)}$	$T_J=25(150)^{\circ}\text{C}$		1.4(1.15)	1.8(1.45)	V
r_F	$T_J=25(150)^{\circ}\text{C}$		6.0(8.4)	6.6(9.0)	m Ω
I_{RRM}	$I_F=300\text{A}; T_J=50^{\circ}\text{C}$		170		A
Q_{rr}	$di/dt=3100\text{A/us}$		79		uC
E_{rr}	$V_{GE}=15\text{V}$		52		mJ
Thermal Characteristics					
$R_{th(j-c)}$	per IGBT			0.094	K/W
$R_{th(j-c)D}$	per Inverse Diode			0.150	K/W
$R_{th(c-s)}$	per module			0.011	K/W
Mechanical Data					
M_s	to heatsink M5	3		6	Nm
M_t	to terminals M6	3		6	Nm
Weight	typical			350	g
Temperature Sensor					
R_{100}	$T_C=100^{\circ}\text{C} (R_{25}=5\text{ k}\Omega)$		493 $\pm$ 5%		Ω
$B_{100/125}$	$R(T)=R_{100}\exp[B_{100/125}(1/T-1/T_{100})]; T[K];$		3550 $\pm$ 2%		K

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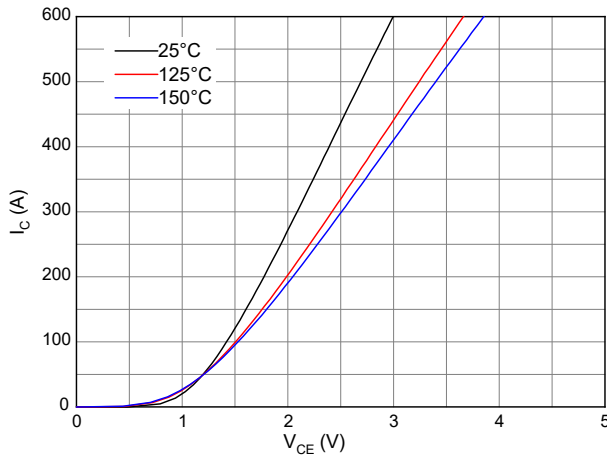


Figure 1. Typical output characteristics ($V_{GE}=15V$)

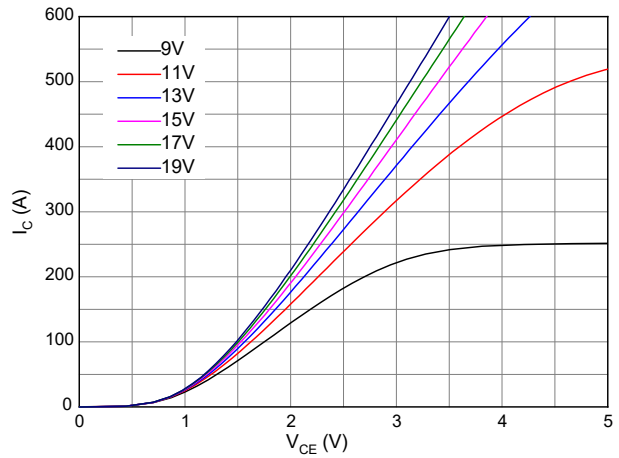


Figure 2. Typical output characteristics ($T_{vj}=150^{\circ}C$)

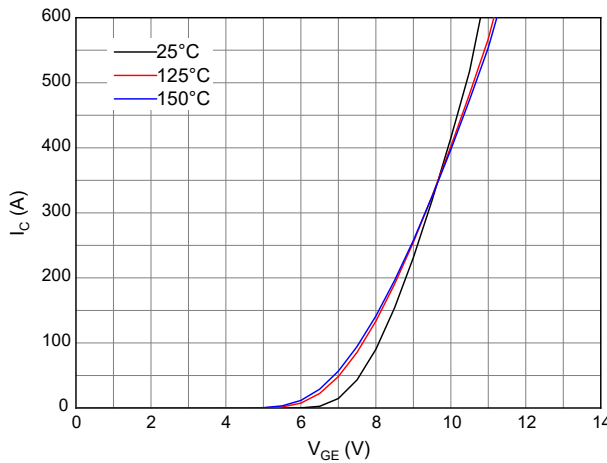


Figure 3. Typical transfer characteristic ($V_{CE}=20V$)

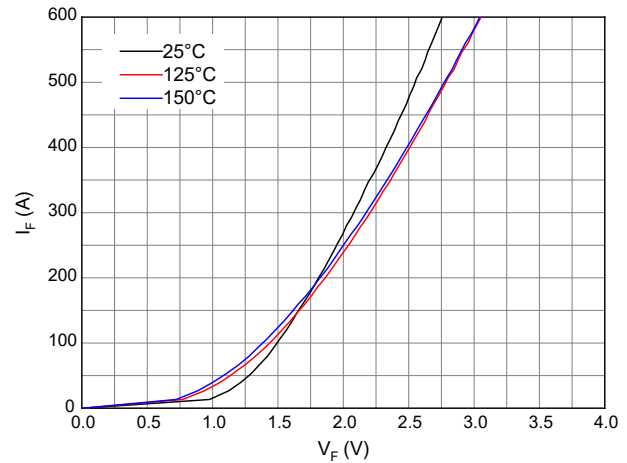


Figure 4. Forward characteristic of Diode

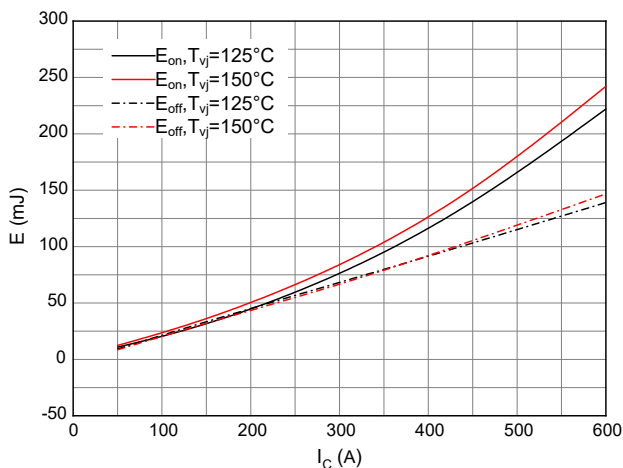


Figure 5. Switching losses of IGBT

$V_{GE}=\pm 15V, R_{Gon}=2.5\Omega, R_{Goff}=2.5\Omega, V_{CE}=900V$

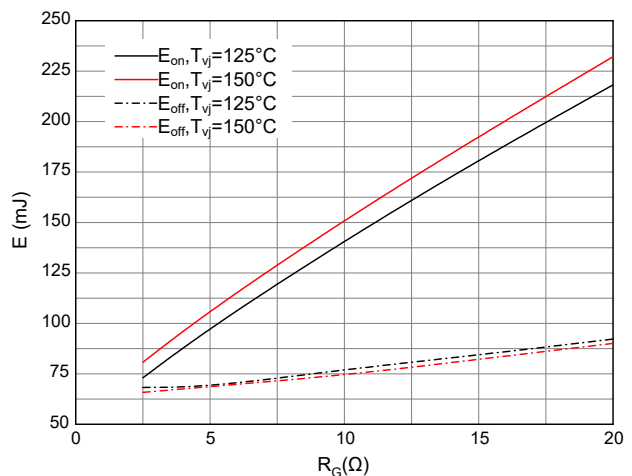


Figure 6. Switching losses of IGBT

$V_{GE}=\pm 15V, I_C=300A, V_{CE}=900V$

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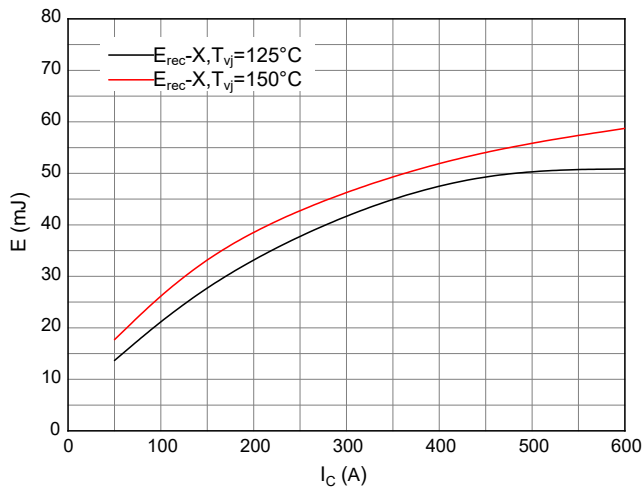


Figure 7. Switching losses of Diode

$R_{Gon}=2.5\Omega$, $V_{CE}=900V$

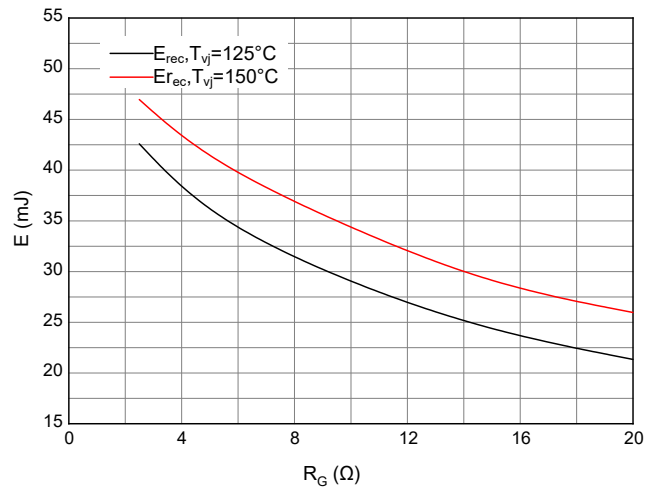


Figure 8. Switching losses of Diode

$I_F=300A$, $V_{CE}=900V$

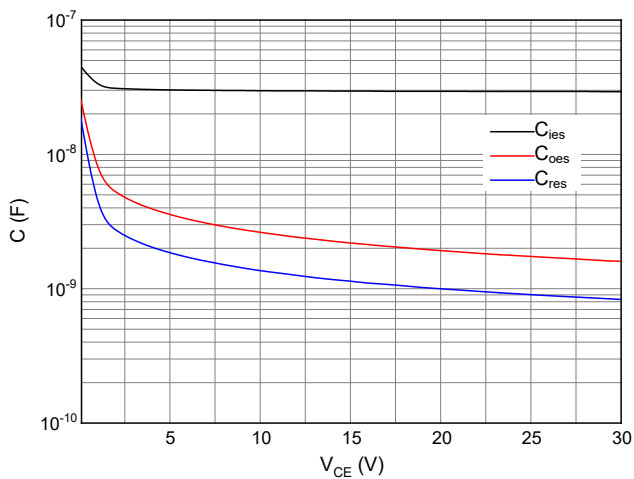


Figure 9. Capacitance characteristic